IN THE CLAIMS

Please amend the claims as follows:

Claims 1-14 (Canceled).

Claim 15 (New): An electromagnetic shielding structure comprising:

a first transparent substrate;

a conducting element deposited on a transparent plastic backing sheet or deposited on the first substrate;

a transparent plastic tie sheet that ties the conducting element to the substrate by the backing sheet being joined to the tie sheet, or that covers the conducting element when the conducting element is deposited directly on the substrate, it being possible for a transparent additional sheet or covering sheet to be optionally joined to the backing sheet against the opposite face to the face joined to the tie sheet or possibly being optionally joined to the tie sheet when the conducting element is deposited directly on the substrate; and

electrical connection means configured to be connected to the conducting element for grounding the conducting element,

wherein at least one of the backing sheet, the tie sheet or the additional sheet or covering sheet, when present, is, at least on one of its sides, placed set back toward an interior of the structure relative to an associated free edge of the transparent substrate so as to leave a portion exposed on at least one of the faces of the conducting element, the connection means being placed against and/or connected to this exposed portion.

Claim 16 (New): The structure as claimed in claim 15, and with the conducting element deposited on the backing sheet, wherein the conducting element is sandwiched between the tie sheet and the backing sheet, and at least the tie sheet is, on at least one of its

sides, placed set back relative to the associated free edge of the transparent substrate so as to leave space for a free part of the transparent substrate and for an exposed portion of the conducting element, this free part facing the exposed portion of the conducting element, and wherein the connection means is fastened by adhesive bonding to the free part of the substrate and is connected via an electrical bonding to that exposed portion of the conducting element facing the free part.

Claim 17 (New): The structure as claimed in claim 15, and with the conducting element deposited on the backing sheet, wherein the conducting element is sandwiched between the tie sheets and the backing sheet, and at least the backing sheet and, when present, the additional sheets are, at least on one of their sides, placed set back relative to the associated free edge of the transparent substrate so as to leave space for an exposed portion of the conducting element, and wherein the connection means is fastened by adhesive bonding and/or by mechanical crimping to the exposed portion of the conducting element.

Claim 18 (New): The structure as claimed in claim 15, and with the conducting element deposited on the backing sheet and including the covering sheet, wherein the conducting element deposited on the backing sheet is placed opposite the tie sheet and sandwiched between the backing sheet and the covering sheet, the covering sheet being, at least on one of its sides, set back toward the interior of the structure relative to the associated free edge of the transparent substrate to leave space for an exposed portion of the conducting element, and wherein the connection means is fastened by adhesive bonding and/or by mechanical crimping to the exposed portion of the conducting element.

Claim 19 (New): The structure as claimed in claim 15, and with the conducting element deposited on the substrate, wherein at least the tie sheet and, when present, the covering sheet are, on at least one of their sides, set back toward the interior of the structure relative to the associated free edge of the transparent substrate to leave the exposed portion of the conducting element accessible, and wherein the connection means is fastened by adhesive bonding and/or by mechanical crimping to the exposed portion of the conducting element.

Claim 20 (New): The structure as claimed in claim 15, wherein the conducting element comprises a silver-based metal layer.

Claim 21 (New): The structure as claimed in claim 16, wherein the conducting element comprises a mesh of conducting wires.

Claim 22 (New): The structure as claimed in claim 15, wherein the connection means comprises a flat conductor, a busbar, or a conductive foam tape.

Claim 23 (New): The structure as claimed in claim 15, wherein all of the periphery of the first substrate of the face situated toward the interior of the structure or the free part of the first substrate is covered with an enamel.

Claim 24 (New): The structure as claimed in claim 15, wherein the exposed portion corresponds, in a manner of a frame, to the entire periphery of one of the faces of the conducting element.

Claim 25 (New): The structure as claimed in claim 15, wherein the backing sheet is made of a plastic, PET, or a material based on one of the following materials: polycarbonate, polymethyl (meth)acrylate, polyethersulfone, polyether-ketone and styrene-acrylonitrile copolymers.

Claim 26 (New): The structure as claimed in claim 15, wherein the tie sheet, the additional sheet, and the covering sheet are made of one of a plastic, polyvinyl butyral, polyurethane, or ethylene-vinyl acetate.

Claim 27 (New): The structure as claimed in claim 15, fitted into a frame, an inner part of which is metallic, the connection means pressing against the inner part.

Claim 28 (New): The structure as claimed in claim 15, joined to a front face of a display, and connected to an electrical ground of the display.